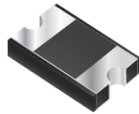


# MATERIAL DECLARATION SHEET



Material Number	CD214C-S3x			
Product Line	Semiconductor Products			
Compliance Date	2017/4/21			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Others	83.34	Continuous filament glass fibers	65997-17-3	43.00	29.8635%	62.05%
				Copper foil	7440-50-8	14.00	9.7230%	
				Non-Hazardous cured resin	Proprietary	43.00	29.8635%	
2	Epoxy	Plastic	30	Silicon Dioxide	7631-86-9	55.00	13.7500%	28.14%
				Epoxy	9003-36-5	45.00	11.2500%	
3	Die Attach	Metal	1.12	Lead <sup>2</sup>	7439-92-1	88.00	0.8213%	2.20%
				Tin	7440-31-5	10.00	0.0933%	
				Silver	7440-22-4	2.00	0.0187%	
4	Dice	Others	3.14	Silicon	7440-21-3	79.85	2.0894%	5.61%
				Nickel	7440-02-0	2.19	0.0573%	
				Aluminum	7429-90-5	0.56	0.0147%	
				Lead Glass <sup>3</sup>	7439-92-1	16.05	0.4200%	
				Phosphorus	7723-14-0	0.28	0.0073%	
				Boron	7440-42-8	0.98	0.0256%	
5	Terminal Plating	Metal	2.4	Misc. not to declare	--	0.09	0.0024%	2.00%
				Tin	7440-31-5	99.9	1.9980%	
			Total weight	120				

This Document was updated on: 11-20-2017

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS Exemption: 7(a)-Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).

3. RoHS Exemption: 7(c)-I- Electrical and electronic components containing lead in a glass or ceramic...